

Low VF Glass Passivated Bridge Rectifiers

Reverse Voltage - 600 Volts Forward Current - 10 Amperes

Features

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- High surge current capability
- •Meet UL flammability classification 94V-0

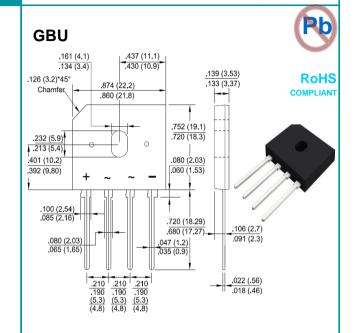
Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

Note: Products with logo or or are made by HY Electronic (Cayman) Limited.

Applications

 General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.



Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

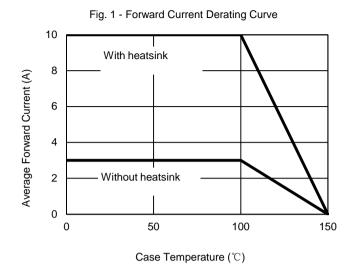
Characteristics	Symbol	GBU1006F	Unit
Maximum Repetitive Peak Reverse Voltage	Vrrm	600	V
Maximum RMS Voltage	VRMS	420	V
Maximum DC Blocking Voltage	VDC	600	V
Maximum Average Forward (with heatsink Note 2)	Iraxa	10.0	۸
Rectified Current @ Tc=100°C (without heatsink)	I(AV)	3.0	A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave,	IFSM	240	
Superimposed on Rated Load (JEDEC Method)	IFSM		A
I ² t Rating for Fusing (t<8.3mS)	l ² t	200.9	A ² s
Peak Forward Voltage per Diode at 5A DC	VF	0.95	V
Maximum DC Reverse Current at Rated @TJ=25°C	lr —	5.0	
DC Bolcking Voltage per Diode @TJ=125°C	IR	500	μA
Typical Junction Capacitance per Diode (Note1)	Cı	70	pF
Typical Thermal Resistance to Ambient (Note2)	Reja	9	
Typical Thermal Resistance to case (Note2)	Rejc	2	°C/W
Typical Thermal Resistance to lead (Note2)	Rejl	1.5	
Operating Junction Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	Тѕтс	-55 to +150	℃

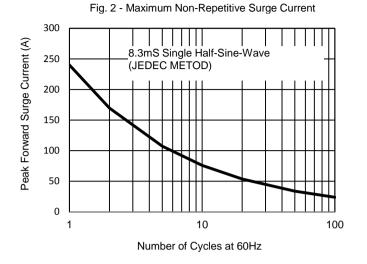
Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

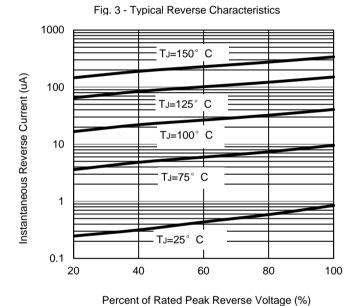
- 2.Device mounted on 100mm*100mm*1.6mm Cu plate heatsink.
- 3. The typical data above is for reference only

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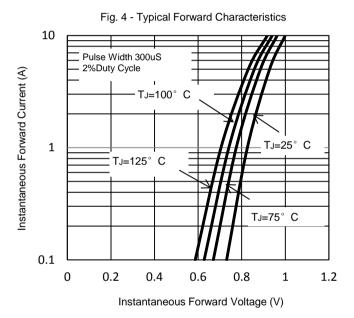
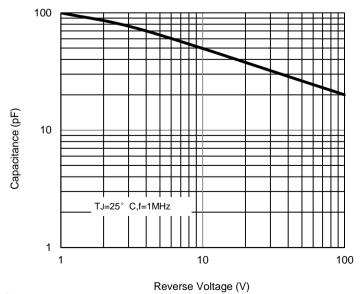


Fig. 5 - Typical Junction Capacitance



The curve above is for reference only.

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ALL specifications and data are subject to be changed without notice to improve reliability function or design or other reasons.

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